

**CITY OF MASSILLON, OHIO
SITE PLAN REVIEW APPLICATION**

The City of Massillon has established a Site Plan Review Committee, which meets on an "as-needed" basis to review Site Plans. A Site Plan must be submitted to the Site Plan Review Committee for approval of any development, except single-family and two-family residential. Building additions or accessory buildings shall not require Site Plan Review Committee approval unless off-street parking in addition to that already provided on the site is required.

Every site plan submitted to the Site Review Committee must include all the information listed on the attached Site Plan Checklist, which contains the minimum requirements.

Application Fees are as follows (Make checks payable to the City of Massillon): \$100.00 plus \$20.00 for each acre of land contained within the development.

The following is to be completed by the Applicant

1. Applicant's Name: Buehrer Group Architecture + Engineers, Inc.
Contact Person: Kent Buehrer Title: President
Address: 314 Conant Street, Miamet, OH 43532
Phone: 419-893-9021 Fax: 419-893-9027 E-Mail: Kent@BuehrerGroup.com
2. Name of Developer: OHIO DEPARTMENT OF TRANSPORTATION - DISTRICT 4
Contact Person: Nathan Crozier Title: Facilities Program Administrator
Address: 2089 S. Arlington Road, Akron, OH 44306
Phone: 330-786-2238 Fax: 330-786-2226 E-Mail: Nathan.Crozier@dot.state.oh.us
3. Name of Site Planner/Engineer: ESA Engineers, Surveyors + Associates LLC
Contact Person: Jeff Ruch Title: Vice President
Address: 5353 Secor Road, Toledo, OH 43623
Phone: 419-475-9445 Fax: 419-475-9473 E-Mail: jruch@esaassociates.com
4. Name of Development: New Massillon Outpost For ODOT
Location/Address of Development: 3018 Richville Drive, SE; Massillon, OH 44646
(If address is not available, provide legal description, lot number, or tax parcel number)
Property Owner's Name: OHIO DEPARTMENT OF TRANSPORTATION

I certify that all required information, as indicated on the attached Checklist, is shown on the Site Plan documents that are hereby submitted as part of this Application.


Applicant's Signature

12/5/2017
Date